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(71) Applicant: NEC KYUSHU LTD

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(72) Inventor: MORI NOBUYUKI

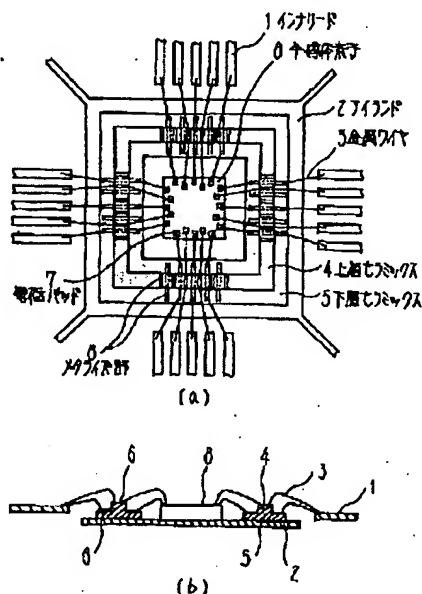
## (54) RESIN-SEALED SEMICONDUCTOR DEVICE

## (57) Abstract:

**PURPOSE:** To easily connect metallic wires and to reduce the size of a semiconductor element by mounting the element on an island on lead frame and connecting a double-layered ceramic extension board surrounded with a conductive layer to pads through the metallic wires.

**CONSTITUTION:** A semiconductor element 8 and ceramic extension board composed of an upper and lower ceramic layers 4 and 5 are mounted on the island of a lead frame. Electrode pads 7 arranged zigzag on the element 8 are connected to the metallized sections 6 of the ceramic layers 4 and 5 through metallic wires 3. At the time of connection, the wires 3 are alternately connected to the metallized sections 6 of the layers 4 and 5 by providing a level difference between each adjacent wires 3. Then the metallized sections 6 of the layers 4 and 5 are connected to inner leads 1 through metallic wires 3 and the element 8 is electrically connected to the inner leads 1.

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